

PMP3940_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C12	0.027uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H273K	TDK
1	C13	4.7uF	Capacitor, Ceramic, 6.3V, X5R	0603	C1608X5R0J475KT	TDK
4	C2, C3, C4, C5	22uF	Capacitor, Ceramic, 16V, X7R	1210	C3225X7R1C226MT	TDK
1	C6	1500pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H152K	TDK
1	C7	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H101K	TDK
2	C8, C14	0.1uF	Capacitor, Ceramic, 0.1uF, 16V, X5R	0603	Std	Std
4	C9, C10, C11, C100	47uF	Capacitor, Ceramic, 6.3V, X5R	1210	C3225X5R0J476MT	TDK
1	J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	J3	{value}	Terminal Block, 2-pin, 32-A, 9.5mm	0.75 x 0.49	ED1981	OST
1	L1	1uH	Inductor, SMT, 23.7A, 1.9-milliohms	0.543 x 0.516 inch	HC9-1R0-R	Cooper
2	Q2, Q3	IRF7466	MOSFET, N-ch, 30-V, 11-A, 12.5-milliohm	SO8	IRF7466	IR
2	Q4, Q5	IRF7832	MOSFET, N-ch, 30-V, 16-A, 4-milliohm	SO8	IRF7832	IR
1	R10	8.87k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	499	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	TP1, TP3, TP4, TP5		Test Point, Red, 1mm	0.038",Farnell"		240-345
2	TP2, TP6		Test Point, Black, 1mm	0.038",Farnell"		240-333
1	TP7		Test Point, Black, 1mm	0.038	240-333	Farnell
1	U1	TPS40190DRC	IC, Low cost synchronous buck controller	DRC10	TPS40190DRC	TI

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